

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Teruaki Chino	12/10/2009
RECEIVING PARTY DATA	
Name:	SHINKO ELECTRIC INDUSTRIES CO., LTD.
Street Address:	80, Oshimada-machi
City:	Nagano-shi, Nagano
State/Country:	JAPAN
Postal Code:	381-2287
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12644477
CORRESPONDENCE DATA	
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	2165669700
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Correspondent Name:	Rankin Hill and Clark LLP
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Address Line 4:	Willoughby, OHIO 44094
ATTORNEY DOCKET NUMBER:	HKY-19705
NAME OF SUBMITTER:	David E. Spaw
Total Attachments: 2 source=19705#page1.tif source=19705#page2.tif	

CH \$40.00 12644477

ASSIGNMENT

WHEREAS, new and useful improvements have been made by the undersigned in
RESIN SEALING METHOD OF SEMICONDUCTOR DEVICE

that are the subject of an application for a U.S. Patent, (Application No. 12/644477,
filed 12/22/2009), which application is further identified as Rankin, Hill &
Clark LLP Docket No. HKY-19705.

WHEREAS, SHINKO ELECTRIC INDUSTRIES CO., LTD., a corporation of
Japan, and having a place of business at
80, OSHIMADA-MACHI, NAGANO-SHI, NAGANO 381-2287, JAPAN, hereinafter
referred to as "assignee", is desirous of acquiring all right, title, and interest throughout
the world in, to, and under said improvements and inventions and patent rights
therefor.

NOW, THEREFORE, be it known that, for valuable consideration, the receipt
and sufficiency of which are hereby acknowledged, all right, title, and interest, in the
United States and throughout the world, in, to and under said improvements and
inventions and all patents, patent applications, patent rights, and inventor's certificates
thereof, therefor, and therein, including without limitation said application for patent in
the United States, all divisions and continuations thereof, all patents which may be
granted thereon, all reissues and extensions thereof, all right to sue for past
infringement thereunder, all patents which may be granted for said improvements and
inventions by states or nations other than the United States, or by other authority,
entity, or organization, and all applications therefor, have been and are hereby sold,
assigned, transferred, and delivered unto assignee, its successors and assigns; and it
is covenanted and agreed by the undersigned, and for executors, administrators, and
legal representatives of the undersigned, that at assignee's request any and all
applications, affidavits, assignments, and other instruments will be made, executed,
and delivered as may be necessary, or desirable to secure for or vest in assignee, its
successors or assigns, any improvement, inventions, right, title, interest, application,
patent, patent right or other right or property covered by this assignment, and the
United States Commissioner of Patents and Trademarks is hereby requested and
authorized to issue any and all United States patents granted on any of said
applications to assignee as owner of the entire right, title, and interest in, to, and under
the same, and appropriately empowered officials of foreign countries are hereby
authorized to issue any letters patent granted on any of said applications to assignee
as owner of the entire right, title and interest in, to, and under the same.

The undersigned hereby grants the firm of Rankin, Hill & Clark LLP the power to
insert on this assignment any identification that may be necessary or desirable in order
to comply with the rules of the United States Patent and Trademark Office for
recordation of this document.

IN WITNESS WHEREOF, this assignment has been executed below by the undersigned:

(1) Inventor Name (sole or joint): Teruaki CHINO
Signature: Teruaki Chino
Today's Date : December 10, 2009

Witness: _____

Witness: _____

(2) Inventor Name (joint): _____
Signature: _____
Today's Date : _____

Witness: _____

Witness: _____

(3) Inventor Name (joint): _____
Signature: _____
Today's Date : _____

Witness: _____

Witness: _____

(4) Inventor Name (joint): _____
Signature: _____
Today's Date : _____

Witness: _____

Witness: _____